

# NOT RECOMMENDED FOR NEW DESIGN -NO ALTERNATE PART

ZXM64N02X

# **Product Summary**

| V <sub>(BR)DSS</sub> | R <sub>DS(ON)</sub> | Ι <sub>D</sub> |
|----------------------|---------------------|----------------|
| 20V                  | 0.040Ω              | 5.4A           |

# Description

This new generation of high density MOSFETs from Diodes Incorporated utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

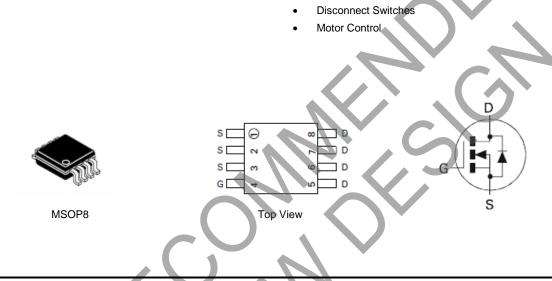
### 20V N-CHANNEL ENHANCEMENT MODE MOSFET

### **Features**

- Low On-resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Low Profile SOIC Package

### **Applications**

- DC DC Converters
- Power Management Functions



# **Ordering Information**

| Part Number | Device Marking | Reel Size (inches) | Tape Width (mm) | Quantity Per Reel |
|-------------|----------------|--------------------|-----------------|-------------------|
| ZXM64N02XTA | ZXM64N02       |                    | 12mm Embossed   | 1000 Units        |
| ZXM64N02XTC | ZXM64N02       | 13                 | 12mm Embossed   | 4000 Units        |





# **Absolute Maximum Ratings**

| PARAMETER   | SYMBOL                           | LIMIT       | UNIT       |
|---|----------------------------------|-------------|------------|
| Drain-Source Voltage  | V <sub>DSS</sub>                 | 20          | V          |
| Gate-Source Voltage   | V <sub>GS</sub>                  | ± 12        | V          |
| Continuous Drain Current ( $V_{GS}=4.5V$ ; $T_A=25^{\circ}C$ )(b)<br>( $V_{GS}=4.5V$ ; $T_A=70^{\circ}C$ )(b) | ID                               | 5.4<br>4.3  | Α          |
| Pulsed Drain Current (c)  | I <sub>DM</sub>                  | 30          | Α          |
| Continuous Source Current (Body Diode)(b)   | I <sub>S</sub>                   | 2.4         | A          |
| Pulsed Source Current (Body Diode)(c)   | I <sub>SM</sub>                  | 30          | A          |
| Power Dissipation at T <sub>A</sub> =25°C (a)<br>Linear Derating Factor                                       | PD                               | 1.1<br>8.8  | W<br>mW/°C |
| Power Dissipation at T <sub>A</sub> =25°C (b)<br>Linear Derating Factor                                       | PD                               | 1.8         | W<br>mW/°C |
| Operating and Storage Temperature Range   | T <sub>j</sub> :T <sub>stg</sub> | -55 to +150 | °C         |

# **Thermal Resistance**

| PARAMETER               | SYMBOL VALUE UNIT         |
|-------------------------|---------------------------|
| Junction to Ambient (a) | R <sub>eJA</sub> 113 °C/W |
| Junction to Ambient (b) | R <sub>BJA</sub> 70 °C/W  |
|                         |                           |

#### NOTES

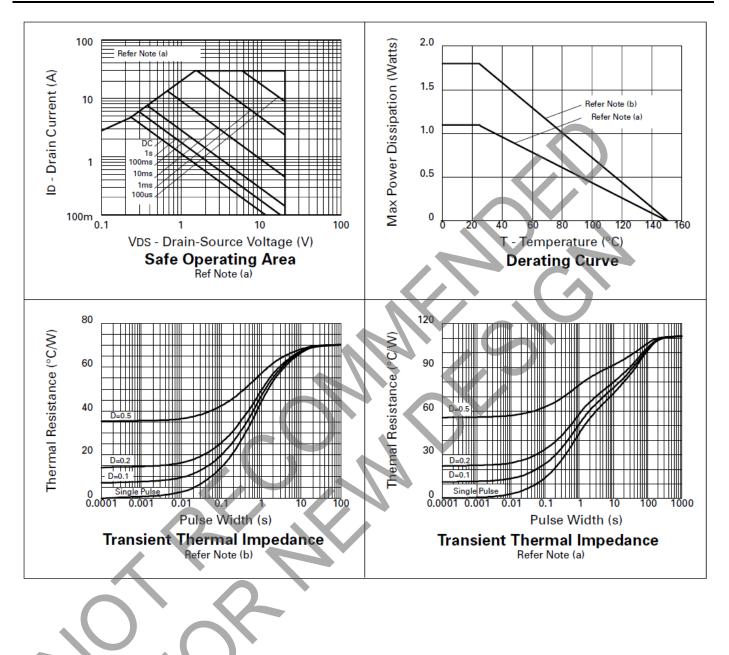
(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at t≤10 secs.

(c) Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.



# **Typical Characteristics**





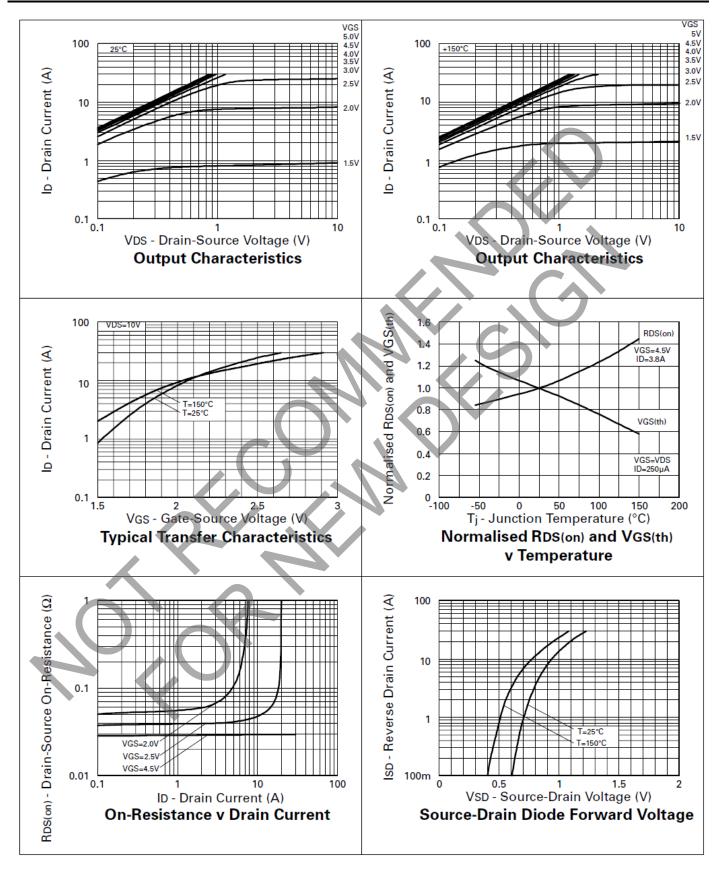
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| PARAMETER                                      | SYMBOL               | MIN. | TYP. | MAX.           | UNIT   | CONDITIONS.   |  |
|--|----------------------|------|------|----------------|--------|---|--|
| STATIC   |                      |      |      |                |        |   |  |
| Drain-Source Breakdown Voltage                 | V <sub>(BR)DSS</sub> | 20   |      |                | V      | I <sub>D</sub> =250μA, V <sub>GS</sub> =0V  |  |
| Zero Gate Voltage Drain Current                | I <sub>DSS</sub>     |      |      | 1              | μA     | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V   |  |
| Gate-Body Leakage                              | I <sub>GSS</sub>     |      |      | 100            | nA     | $V_{GS}=\pm 12V, V_{DS}=0V$   |  |
| Gate-Source Threshold Voltage                  | V <sub>GS(th)</sub>  | 0.7  |      |                | V      | $I_D = 250 \mu A$ , $V_{DS} = V_{GS}$   |  |
| Static Drain-Source On-State Resistance<br>(1) | R <sub>DS(on)</sub>  |      |      | 0.040<br>0.050 | Ω<br>Ω | V <sub>GS</sub> =4.5V, I <sub>D</sub> =3.8A<br>V <sub>GS</sub> =2.7V, I <sub>D</sub> =1.9A                                  |  |
| Forward Transconductance (3)                   | g <sub>fs</sub>      | 6.1  |      |                | S      | V <sub>DS</sub> =10V,I <sub>D</sub> =1.9A   |  |
| DYNAMIC (3)                                    |                      |      |      |                |        |   |  |
| Input Capacitance                              | Ciss                 |      | 1100 |                | pF     |   |  |
| Output Capacitance                             | Coss                 |      | 350  |                | pF     | V <sub>DS</sub> =15 V, V <sub>GS</sub> =0V,<br>f=1MHz   |  |
| Reverse Transfer Capacitance                   | C <sub>rss</sub>     |      | 100  |                | pF     |   |  |
| SWITCHING(2) (3)                               |                      |      |      |                |        |   |  |
| Turn-On Delay Time                             | t <sub>d(on)</sub>   |      | 5.7  |                | ns     |   |  |
| Rise Time                                      | t <sub>r</sub>       |      | 9.6  |                | nŝ     | $V_{DD}$ = 10V, $I_{D}$ = 3.8A<br>R <sub>G</sub> =6.2 $\Omega$ , R <sub>D</sub> =2.6 $\Omega$<br>(Refer to test<br>circuit) |  |
| Turn-Off Delay Time                            | t <sub>d(off)</sub>  |      | 28.3 |                | ns     |   |  |
| Fall Time                                      | t <sub>f</sub>       |      | 11.6 |                | ns     |   |  |
| Total Gate Charge                              | Qg                   |      |      | 16             | nC     |   |  |
| Gate-Source Charge                             | Q <sub>gs</sub>      |      |      | 3.5            | nC     | V <sub>DS</sub> =16V,V <sub>GS</sub> =4.5V,<br>I <sub>D</sub> =3.8A<br>(Refer to test<br>circuit)                           |  |
| Gate Drain Charge                              | Q <sub>gd</sub>      |      |      | 5.4            | nC     |   |  |
| SOURCE-DRAIN DIODE                             |                      |      | 1    |                |        |   |  |
| Diode Forward Voltage (1)                      | Vsd                  | #    |      | 0.95           | V      | T <sub>j</sub> =25°C, I <sub>S</sub> =3.8A,<br>V <sub>GS</sub> =0V  |  |
| Reverse Recovery Time (3)                      | t <sub>rr</sub>      |      | 23.7 |                | ns     | T <sub>j</sub> =25°C, I <sub>F</sub> =3.8A,   |  |
| Reverse Recovery Charge(3)                     | Q <sub>rr</sub>      |      | 13.3 |                | nC     | di/dt= 100A/µs  |  |

(1) Measured under pulsed conditions. Width=300µs. Duty cycle ≤2%.
(2) Switching characteristics are independent of operating junction temperature.
(3) For design aid only, not subject to production testing.

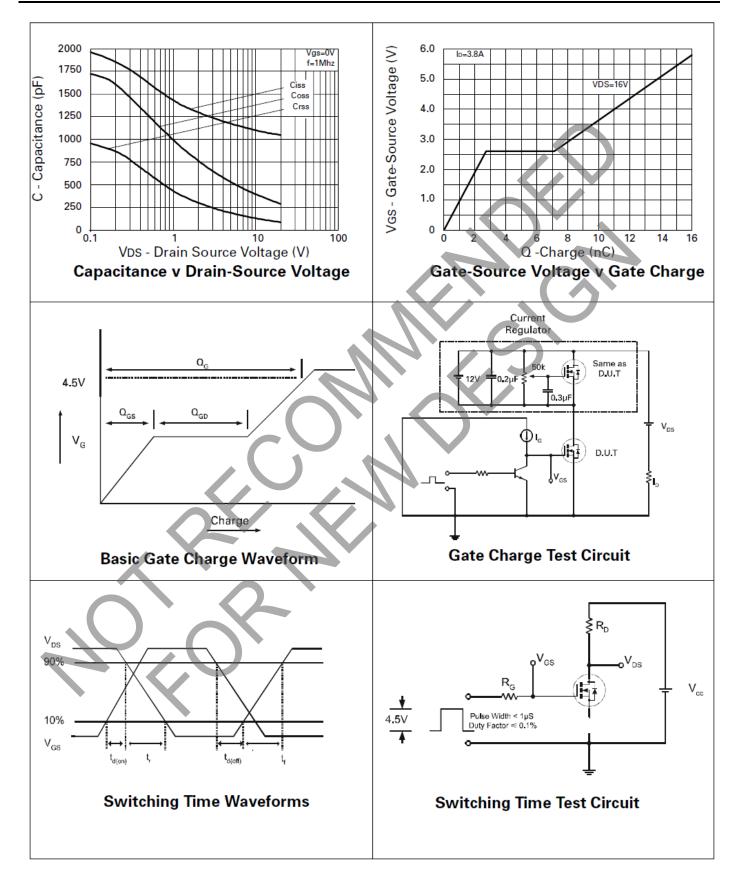


# **Typical Characteristics**





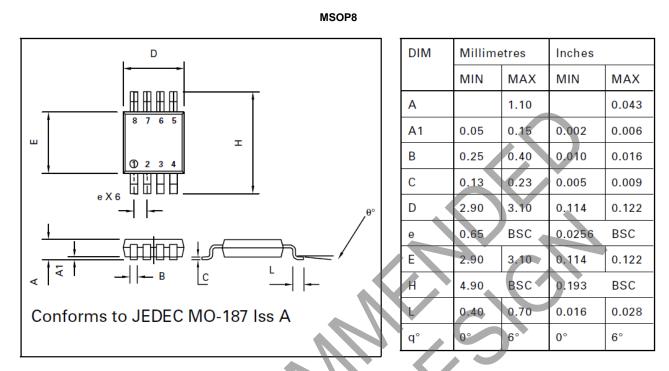
# Typical Characteristics (Cont.)





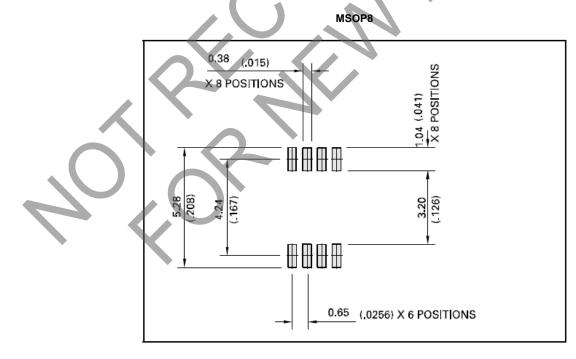
# Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





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